

STARPOWER

SEMICONDUCTOR

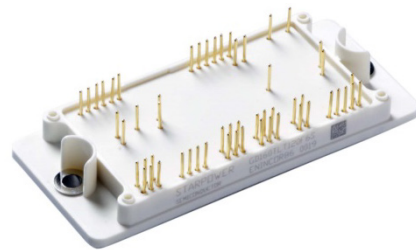
IGBT

GD160TLT120F6S

1200V/160A 3-level in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as UPS and solar power.



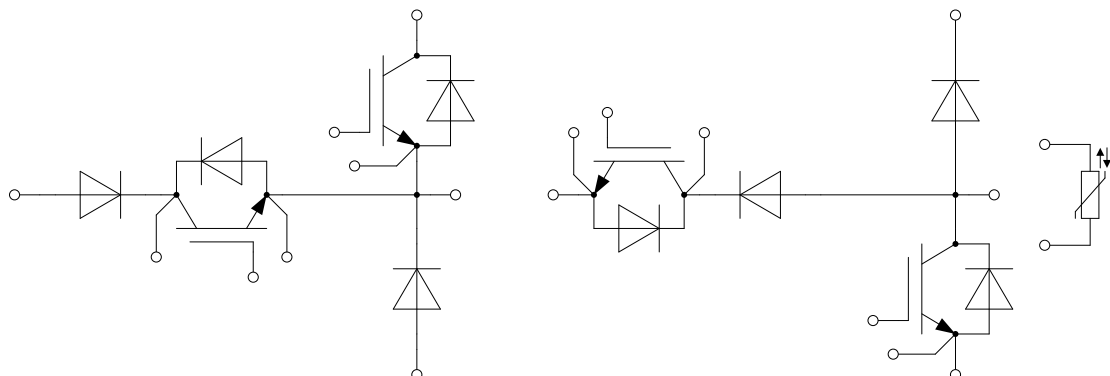
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- Low switching loss
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD

Typical Applications

- 3-level-applications
- Uninterruptible power supply
- Solar Power

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**T1,T6 IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$	240	A
	@ $T_C=100^{\circ}\text{C}$	160	A
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	320	A
P_D	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	968	W

D1,D6 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	25	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	50	A

D2,D5 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	50	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	100	A

T4,T7 IGBT

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^\circ\text{C}$	140	A
	@ $T_C=85^\circ\text{C}$	100	A
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	200	A
P_D	Maximum Power Dissipation @ $T_j=175^\circ\text{C}$	360	W

D4,D7 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	650	V
I_F	Diode Continuous Forward Current	50	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	100	A

D3,D8 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	650	V
I_F	Diode Continuous Forward Current	100	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	200	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^\circ\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^\circ\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	4000	V

T1,T6 IGBT Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=160\text{A}, V_{GE}=15\text{V}, T_j=25^\circ\text{C}$		2.05	2.40	V	
		$I_C=160\text{A}, V_{GE}=15\text{V}, T_j=125^\circ\text{C}$		2.50			
		$I_C=160\text{A}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}$		2.60			
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=6.0\text{mA}, V_{CE}=V_{GE}, T_j=25^\circ\text{C}$	5.3	5.8	6.3	V	
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$			1.0	mA	
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^\circ\text{C}$			400	nA	
R_{Gint}	Internal Gate Resistance			0		Ω	
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=1\text{MHz}, V_{GE}=0\text{V}$		4.66		nF	
C_{res}	Reverse Transfer Capacitance			0.23		nF	
Q_G	Gate Charge	$V_{GE}=15\text{V}$		0.74		μC	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=160\text{A}, R_G=4.1\Omega, V_{GE}=\pm 15\text{V}, T_j=25^\circ\text{C}$		180		ns	
t_r	Rise Time			55		ns	
$t_{d(off)}$	Turn-Off Delay Time			225		ns	
t_f	Fall Time			140		ns	
E_{on}	Turn-On Switching Loss			7.40		mJ	
E_{off}	Turn-Off Switching Loss			5.52		mJ	
$t_{d(on)}$	Turn-On Delay Time		$V_{CC}=600\text{V}, I_C=160\text{A}, R_G=4.1\Omega, V_{GE}=\pm 15\text{V}, T_j=125^\circ\text{C}$		185		ns
t_r	Rise Time				58		ns
$t_{d(off)}$	Turn-Off Delay Time			250		ns	
t_f	Fall Time			195		ns	
E_{on}	Turn-On Switching Loss			12.5		mJ	
E_{off}	Turn-Off Switching Loss			9.28		mJ	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=160\text{A}, R_G=4.1\Omega, V_{GE}=\pm 15\text{V}, T_j=150^\circ\text{C}$			186		ns
t_r	Rise Time				59		ns
$t_{d(off)}$	Turn-Off Delay Time			255		ns	
t_f	Fall Time			205		ns	
E_{on}	Turn-On Switching Loss			12.7		mJ	
E_{off}	Turn-Off Switching Loss			9.48		mJ	
I_{SC}	SC Data		$t_p \leq 10\mu\text{s}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}, V_{CC}=900\text{V}, V_{CEM} \leq 1200\text{V}$		640		A

D1,D6 Diode Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=25\text{A}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$		2.10	2.45	V
		$I_F=25\text{A}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$		2.15		
		$I_F=25\text{A}, V_{GE}=0\text{V}, T_j=150^\circ\text{C}$		2.15		
Q_r	Recovered Charge	$V_R=600\text{V}, I_F=25\text{A},$ $-di/dt=900\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^\circ\text{C}$		1.3		μC
I_{RM}	Peak Reverse Recovery Current			31		A
E_{rec}	Reverse Recovery Energy			0.68		mJ
Q_r	Recovered Charge	$V_R=600\text{V}, I_F=25\text{A},$ $-di/dt=900\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^\circ\text{C}$		2.2		μC
I_{RM}	Peak Reverse Recovery Current			38		A
E_{rec}	Reverse Recovery Energy			1.46		mJ
Q_r	Recovered Charge	$V_R=600\text{V}, I_F=25\text{A},$ $-di/dt=900\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^\circ\text{C}$		2.4		μC
I_{RM}	Peak Reverse Recovery Current			40		A
E_{rec}	Reverse Recovery Energy			1.91		mJ

D2,D5 Diode Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=50\text{A}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$		1.70	2.05	V
		$I_F=50\text{A}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$		1.65		
		$I_F=50\text{A}, V_{GE}=0\text{V}, T_j=150^\circ\text{C}$		1.65		
Q_r	Recovered Charge	$V_R=600\text{V}, I_F=50\text{A},$ $-di/dt=1200\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^\circ\text{C}$		3.0		μC
I_{RM}	Peak Reverse Recovery Current			46		A
E_{rec}	Reverse Recovery Energy			1.72		mJ
Q_r	Recovered Charge	$V_R=600\text{V}, I_F=50\text{A},$ $-di/dt=1200\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^\circ\text{C}$		7.2		μC
I_{RM}	Peak Reverse Recovery Current			56		A
E_{rec}	Reverse Recovery Energy			3.15		mJ
Q_r	Recovered Charge	$V_R=600\text{V}, I_F=50\text{A},$ $-di/dt=1200\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^\circ\text{C}$		7.8		μC
I_{RM}	Peak Reverse Recovery Current			57		A
E_{rec}	Reverse Recovery Energy			3.24		mJ

T4,T7 IGBT Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=100\text{A}, V_{GE}=15\text{V}, T_j=25^\circ\text{C}$		1.45	1.90	V	
		$I_C=100\text{A}, V_{GE}=15\text{V}, T_j=125^\circ\text{C}$		1.60			
		$I_C=100\text{A}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}$		1.70			
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1.6\text{mA}, V_{CE}=V_{GE}, T_j=25^\circ\text{C}$	5.1	5.8	6.4	V	
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$			1.0	mA	
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^\circ\text{C}$			400	nA	
R_{Gint}	Internal Gate Resistance			0		Ω	
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=1\text{MHz}, V_{GE}=0\text{V}$		6.28		nF	
C_{res}	Reverse Transfer Capacitance			0.19		nF	
Q_G	Gate Charge	$V_{GE}=15\text{V}$		0.62		μC	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=100\text{A}, R_G=4.1\Omega, V_{GE}=\pm 15\text{V}, T_j=25^\circ\text{C}$		195		ns	
t_r	Rise Time			67		ns	
$t_{d(off)}$	Turn-Off Delay Time			236		ns	
t_f	Fall Time			140		ns	
E_{on}	Turn-On Switching Loss			1.04		mJ	
E_{off}	Turn-Off Switching Loss			2.96		mJ	
$t_{d(on)}$	Turn-On Delay Time		$V_{CC}=300\text{V}, I_C=100\text{A}, R_G=4.1\Omega, V_{GE}=\pm 15\text{V}, T_j=125^\circ\text{C}$		195		ns
t_r	Rise Time				69		ns
$t_{d(off)}$	Turn-Off Delay Time			246		ns	
t_f	Fall Time			184		ns	
E_{on}	Turn-On Switching Loss			1.25		mJ	
E_{off}	Turn-Off Switching Loss			3.79		mJ	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=100\text{A}, R_G=4.1\Omega, V_{GE}=\pm 15\text{V}, T_j=150^\circ\text{C}$			196		ns
t_r	Rise Time				70		ns
$t_{d(off)}$	Turn-Off Delay Time			249		ns	
t_f	Fall Time			200		ns	
E_{on}	Turn-On Switching Loss			1.30		mJ	
E_{off}	Turn-Off Switching Loss			4.09		mJ	
I_{SC}	SC Data		$t_p \leq 6\mu\text{s}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}, V_{CC}=360\text{V}, V_{CEM} \leq 650\text{V}$		500		A

D4,D7 Diode Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=50\text{A}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$		1.35	1.70	V
		$I_F=50\text{A}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$		1.37		
		$I_F=50\text{A}, V_{GE}=0\text{V}, T_j=150^\circ\text{C}$		1.40		
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=50\text{A},$ $-di/dt=1600\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^\circ\text{C}$		2.3		μC
I_{RM}	Peak Reverse Recovery Current			33		A
E_{rec}	Reverse Recovery Energy			0.56		mJ
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=50\text{A},$ $-di/dt=1600\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^\circ\text{C}$		4.3		μC
I_{RM}	Peak Reverse Recovery Current			58		A
E_{rec}	Reverse Recovery Energy			1.11		mJ
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=50\text{A},$ $-di/dt=1600\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^\circ\text{C}$		5.1		μC
I_{RM}	Peak Reverse Recovery Current			60		A
E_{rec}	Reverse Recovery Energy			1.22		mJ

D3,D8 Diode Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=100\text{A}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$		1.55	1.95	V
		$I_F=100\text{A}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$		1.50		
		$I_F=100\text{A}, V_{GE}=0\text{V}, T_j=150^\circ\text{C}$		1.45		
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=100\text{A},$ $-di/dt=1600\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^\circ\text{C}$		3.6		μC
I_{RM}	Peak Reverse Recovery Current			34		A
E_{rec}	Reverse Recovery Energy			1.16		mJ
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=100\text{A},$ $-di/dt=1600\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^\circ\text{C}$		6.7		μC
I_{RM}	Peak Reverse Recovery Current			61		A
E_{rec}	Reverse Recovery Energy			2.03		mJ
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=100\text{A},$ $-di/dt=1600\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^\circ\text{C}$		7.5		μC
I_{RM}	Peak Reverse Recovery Current			62		A
E_{rec}	Reverse Recovery Energy			2.40		mJ

NTC Characteristics $T_c=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			22.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of R_{100}	$T_c=100^{\circ}\text{C}, R_{100}=1486.1\Omega$	-5		5	%
P_{25}	Power Dissipation				200	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		4000		K

Module Characteristics $T_c=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
$R_{\theta JC}$	Junction-to-Case (per T1,T6 IGBT)		0.141		K/W
	Junction-to-Case (per D1,D6 Diode)		1.210		
	Junction-to-Case (per D2,D5 Diode)		0.681		
	Junction-to-Case (per T4,T7 IGBT)		0.379		
	Junction-to-Case (per D4,D7 Diode)		1.041		
	Junction-to-Case (per D3,D8 Diode)		0.694		
$R_{\theta CS}$	Case-to-Sink (per T1,T6 IGBT)		0.069		K/W
	Case-to-Sink (per D1,D6 Diode)		0.594		
	Case-to-Sink (per D2,D5 Diode)		0.334		
	Case-to-Sink (per T4,T7 IGBT)		0.186		
	Case-to-Sink (per D4,D7 Diode)		0.511		
	Case-to-Sink (per D3,D8 Diode)		0.340		
$R_{\theta CS}$	Case-to-Sink		0.017		K/W
M	Mounting Torque, Screw M5	3.0		6.0	N.m

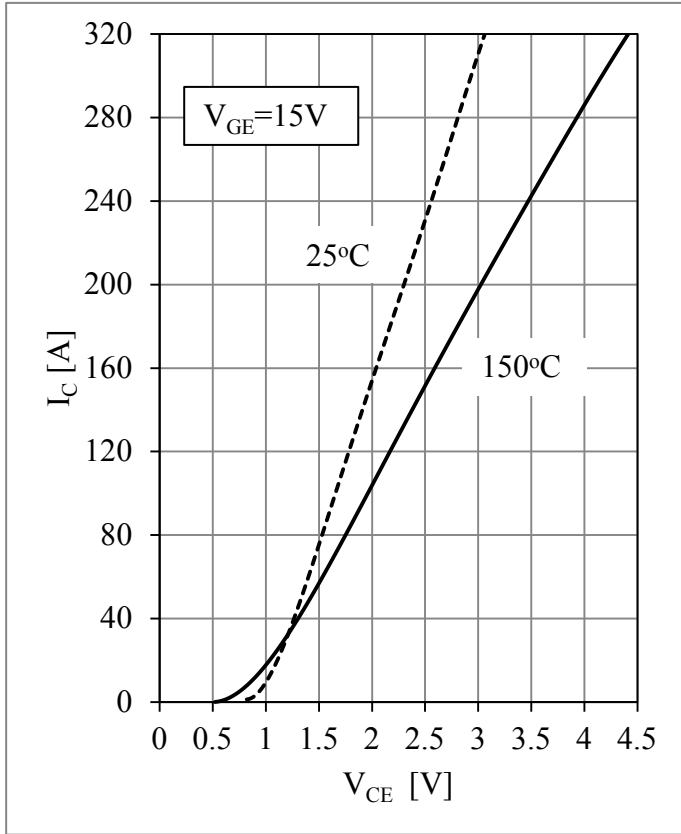


Fig 1. T1,T6 IGBT Output Characteristics

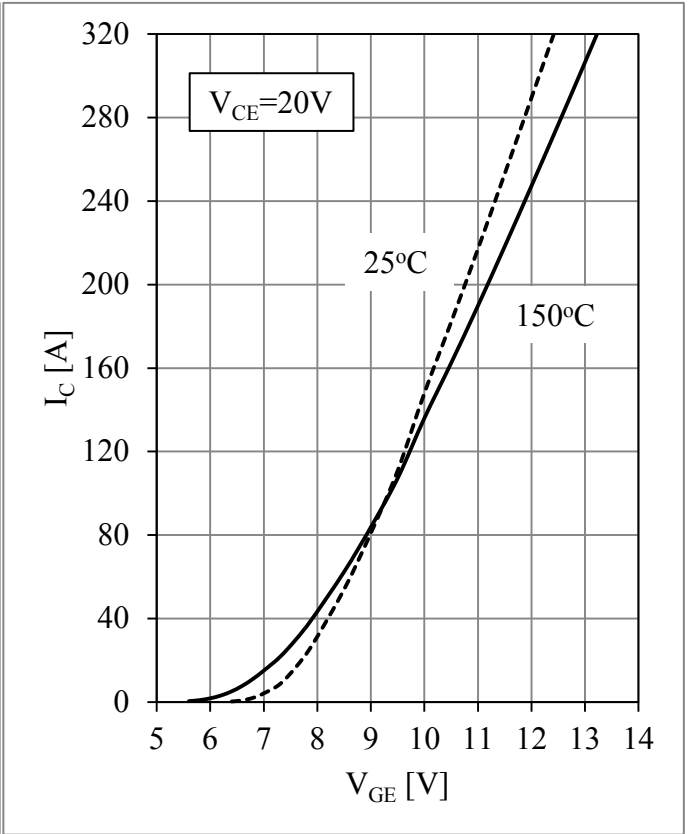


Fig 2. T1,T6 IGBT Transfer Characteristics

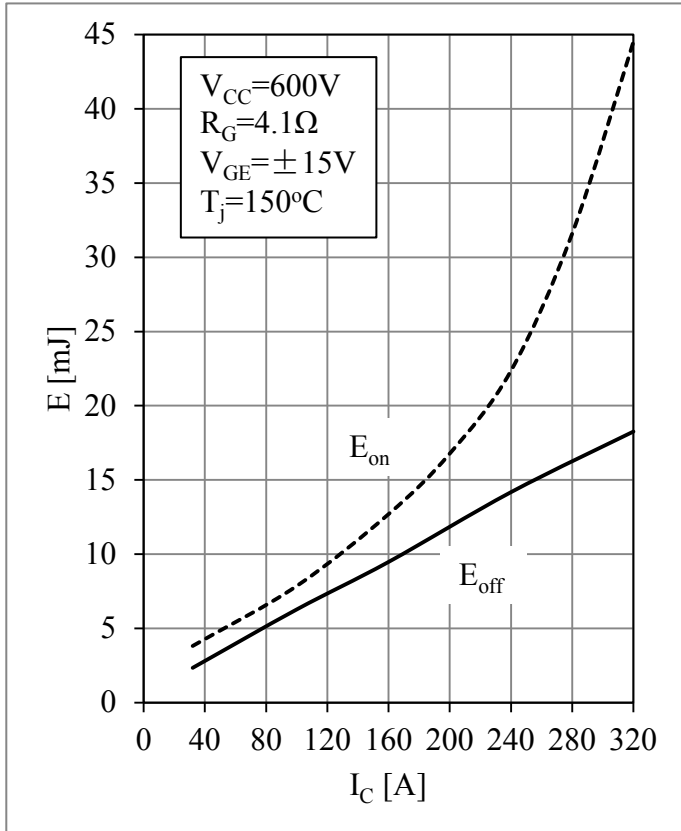


Fig 3. T1,T6 IGBT Switching Loss vs. I_c

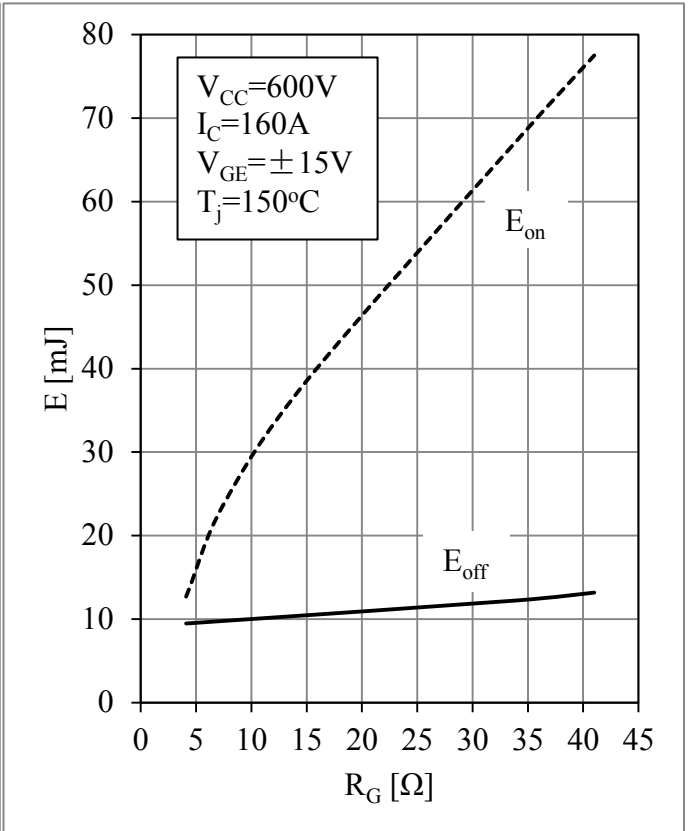


Fig 4. T1,T6 IGBT Switching Loss vs. R_G

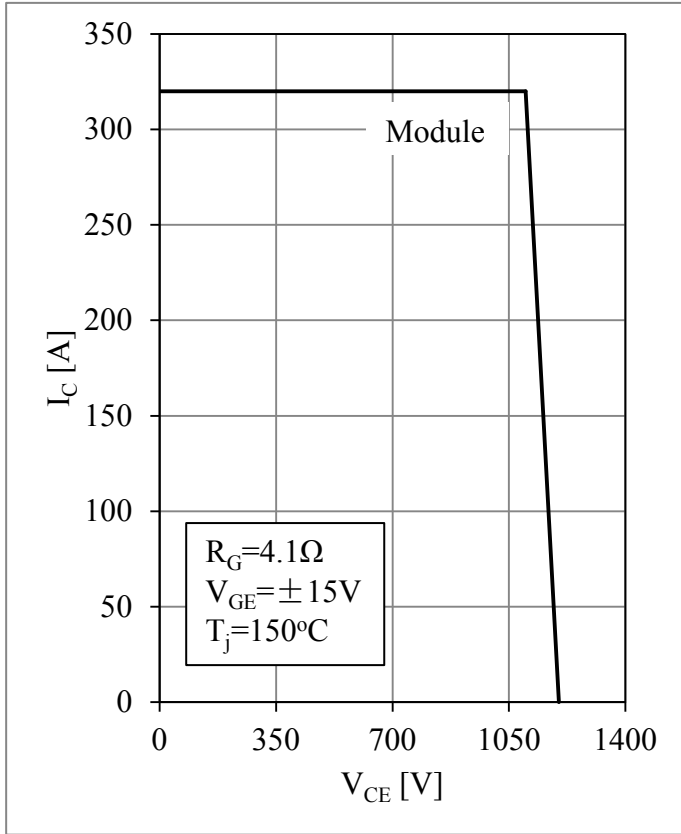


Fig 5. T1,T6 RBSOA

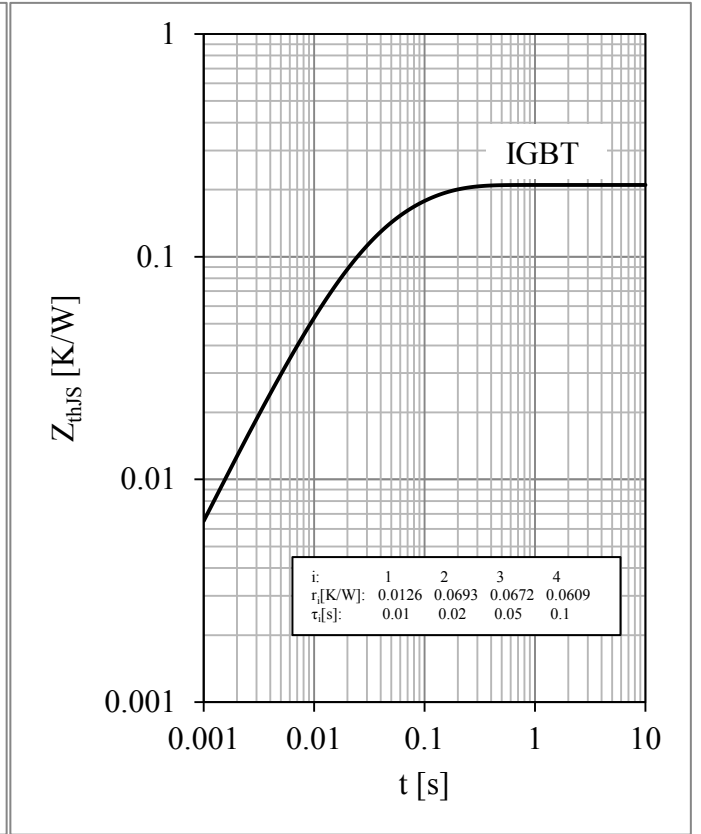


Fig 6. T1,T6 IGBT Transient Thermal Impedance

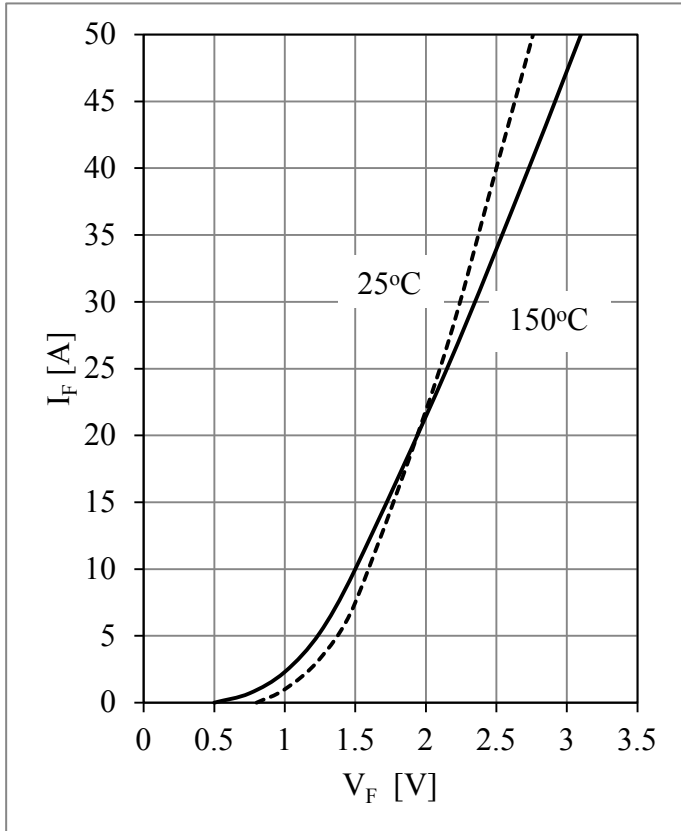


Fig 7. D1,D6 Diode Forward Characteristics

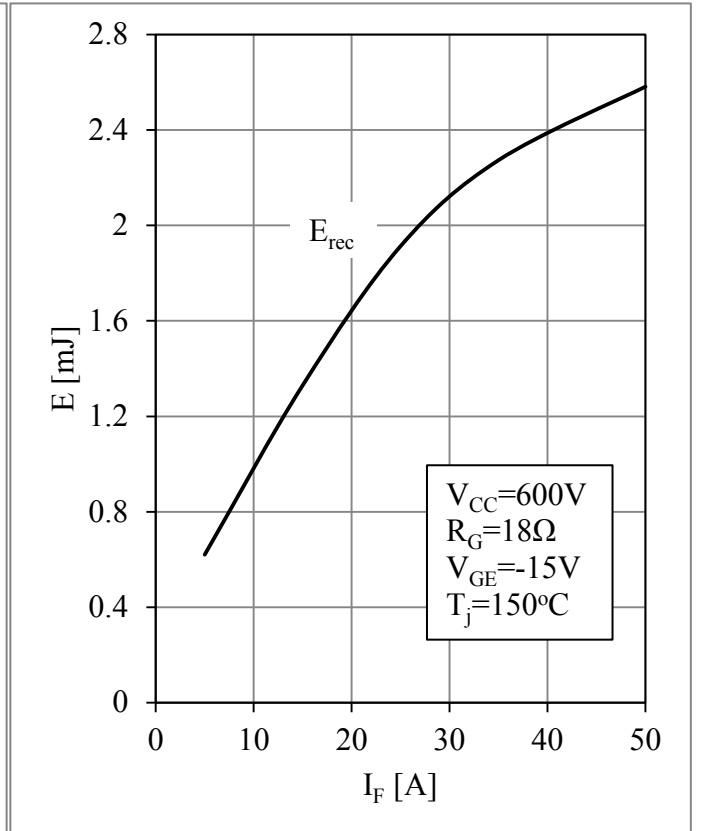


Fig 8. D1,D6 Diode Switching Loss vs. I_F

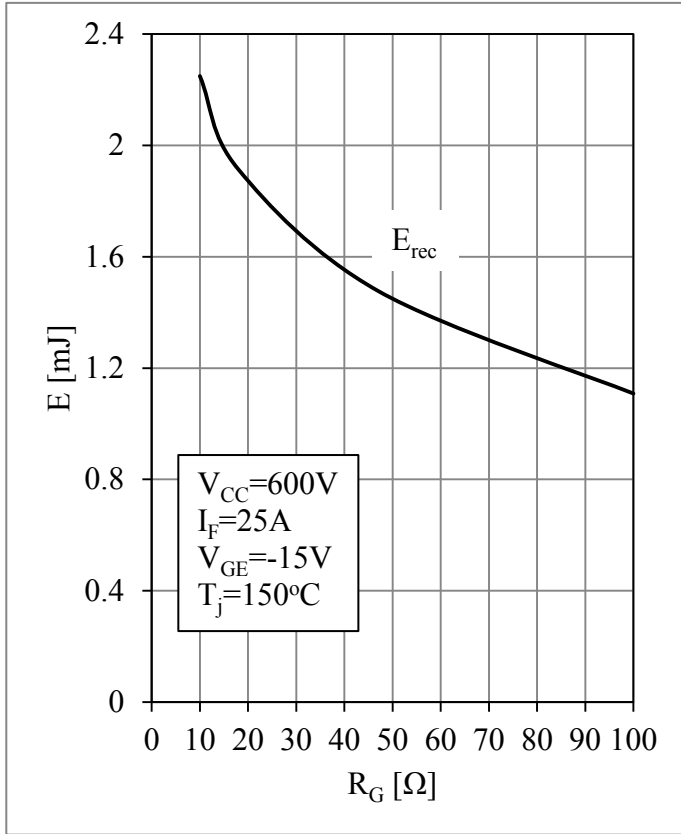


Fig 9. D1,D6 Diode Switching Loss vs. R_G

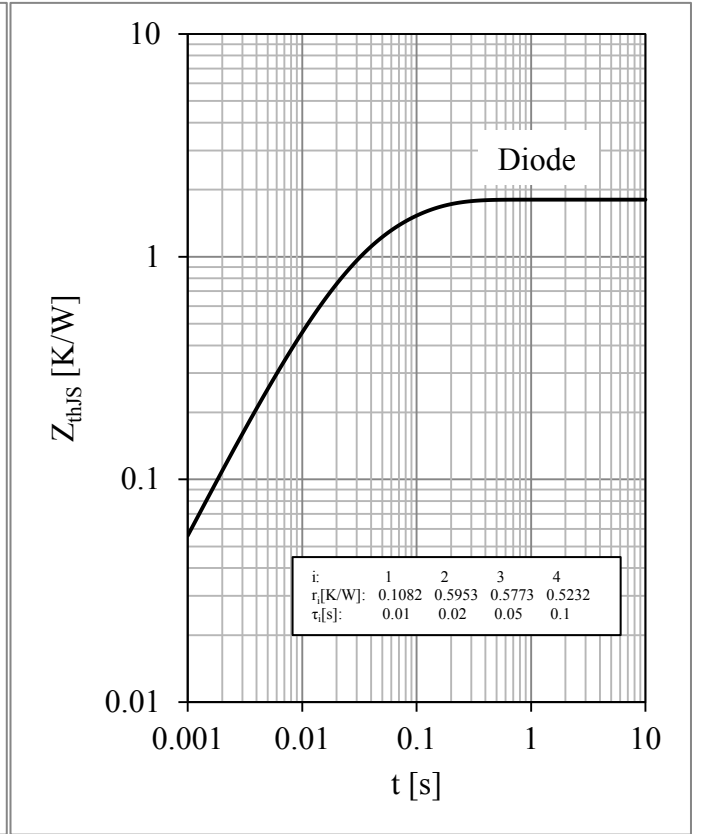


Fig 10. D1,D6 Diode Transient Thermal Impedance

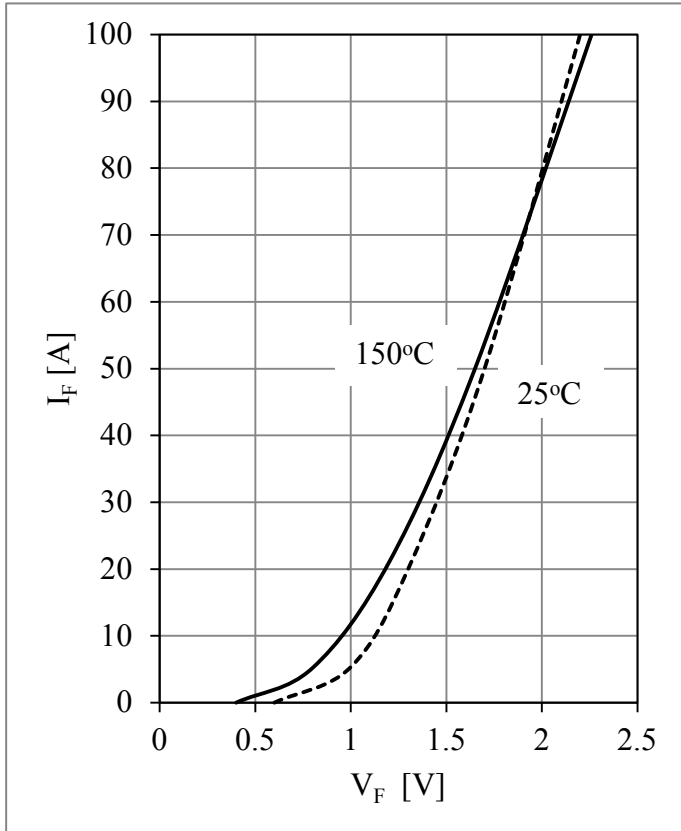


Fig 11. D2,D5 Diode Forward Characteristics

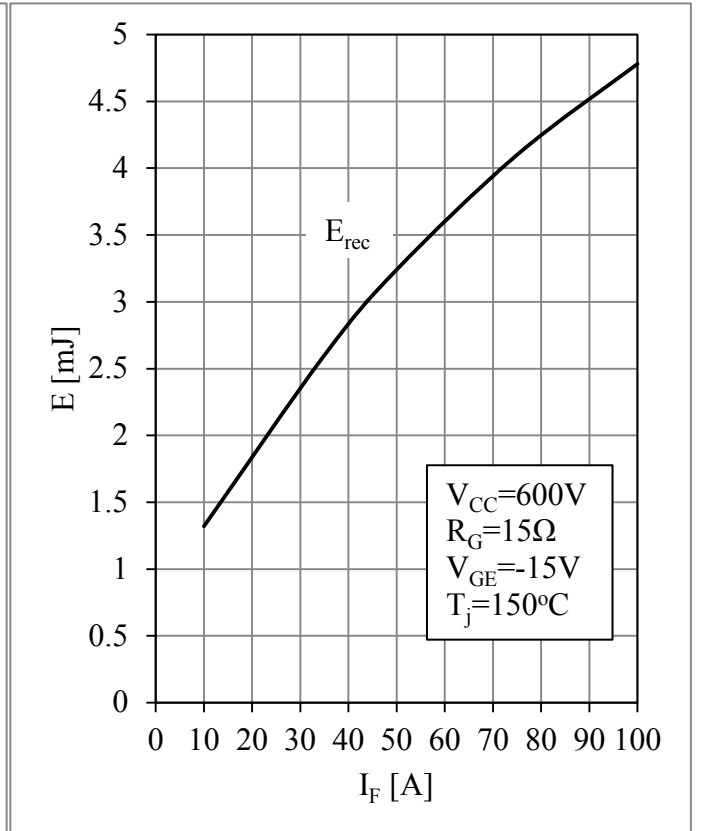


Fig 12. D2,D5 Diode Switching Loss vs. I_F

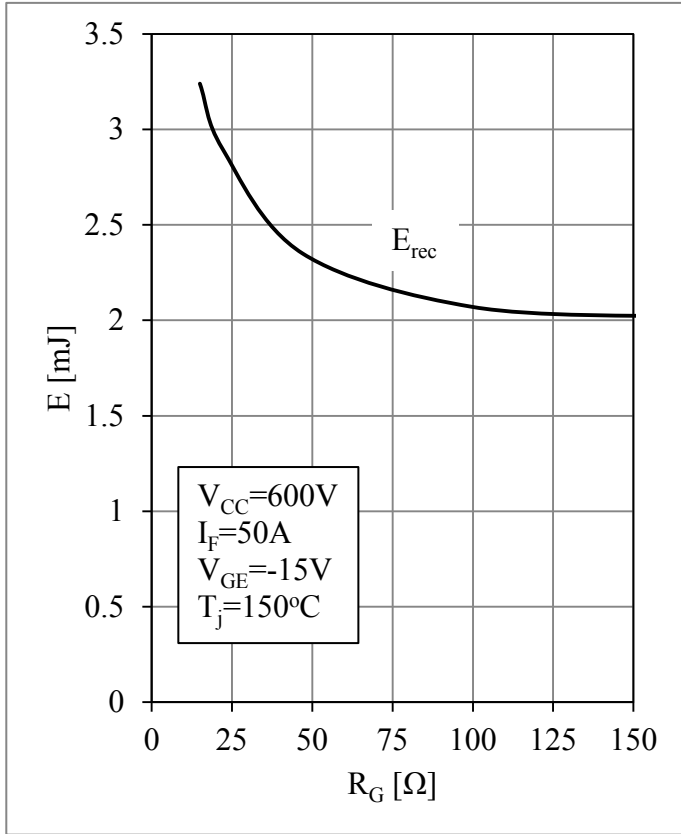


Fig 13. D2,D5 Diode Switching Loss vs. R_G

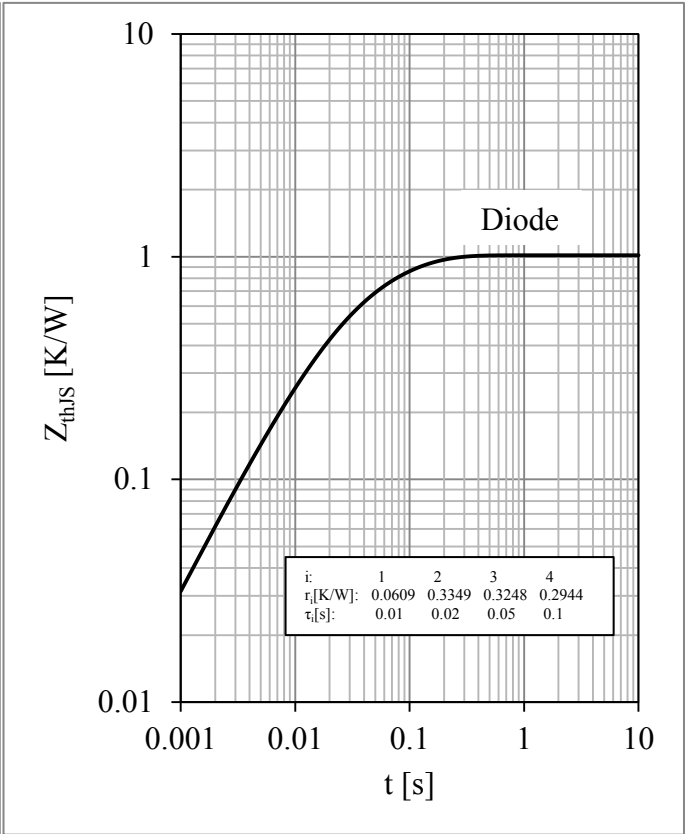


Fig 14. D2,D5 Diode Transient Thermal Impedance

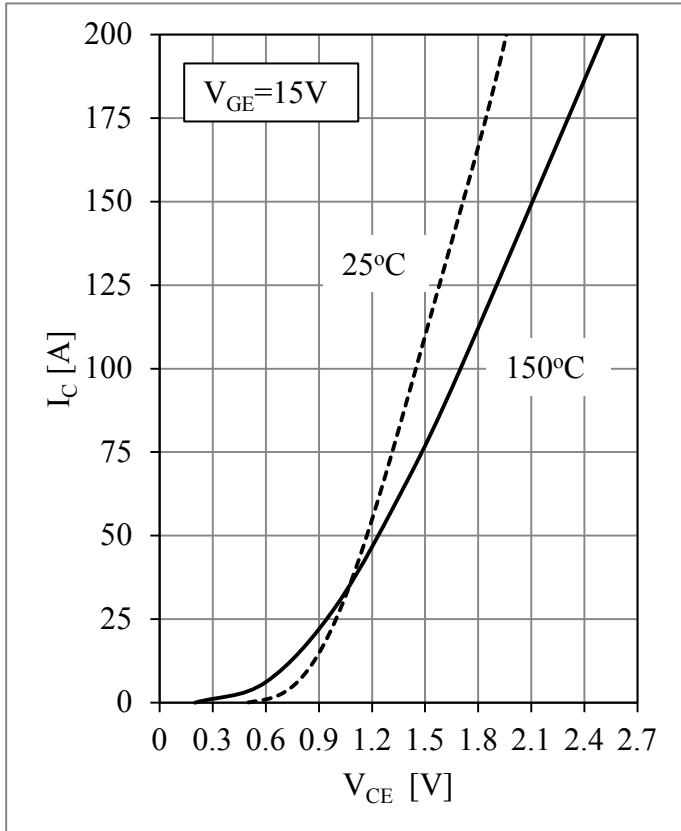


Fig 15. T4,T7 IGBT Output Characteristics

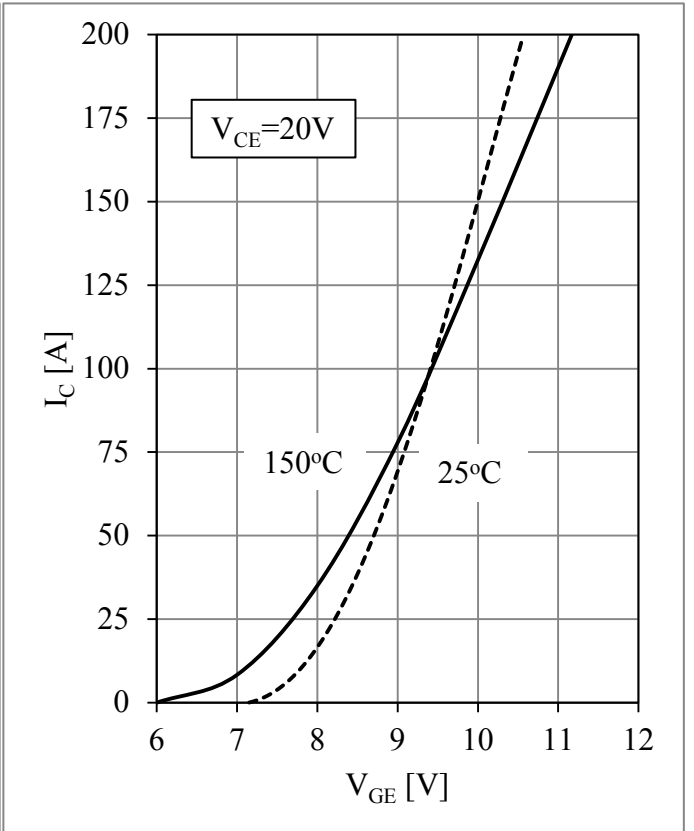


Fig 16. T4,T7 IGBT Transfer Characteristics

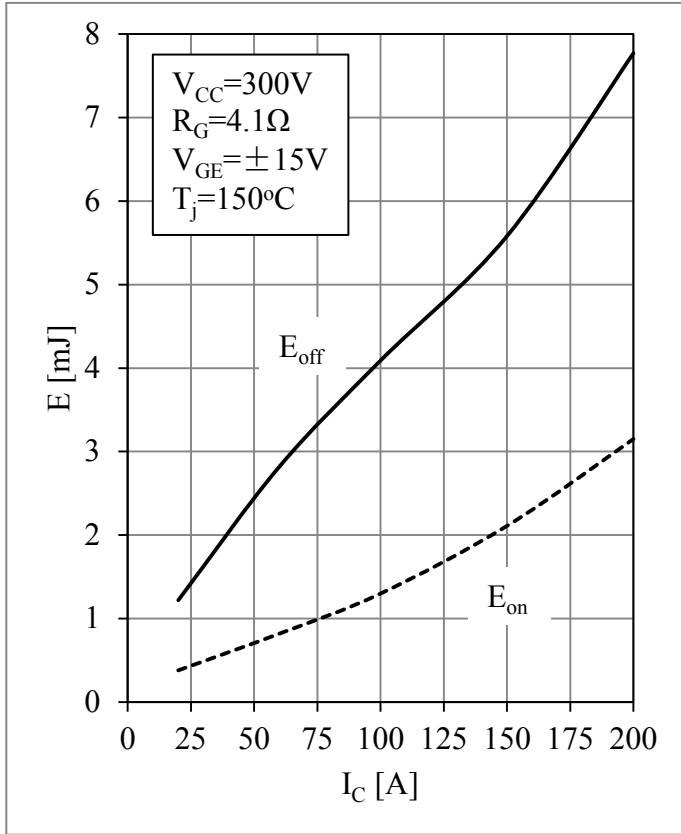


Fig 17. T4,T7 IGBT Switching Loss vs. I_C

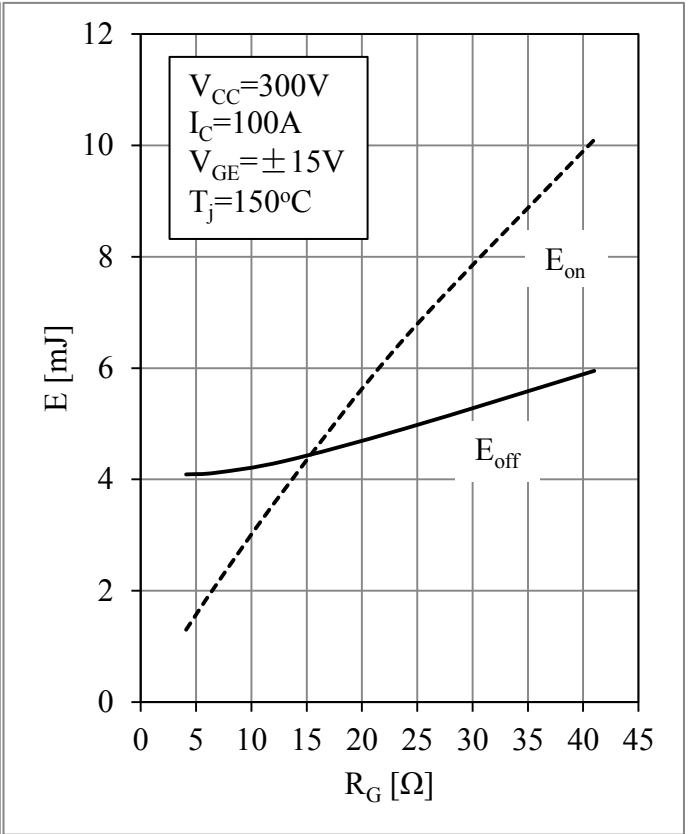


Fig 18. T4,T7 IGBT Switching Loss vs. R_G

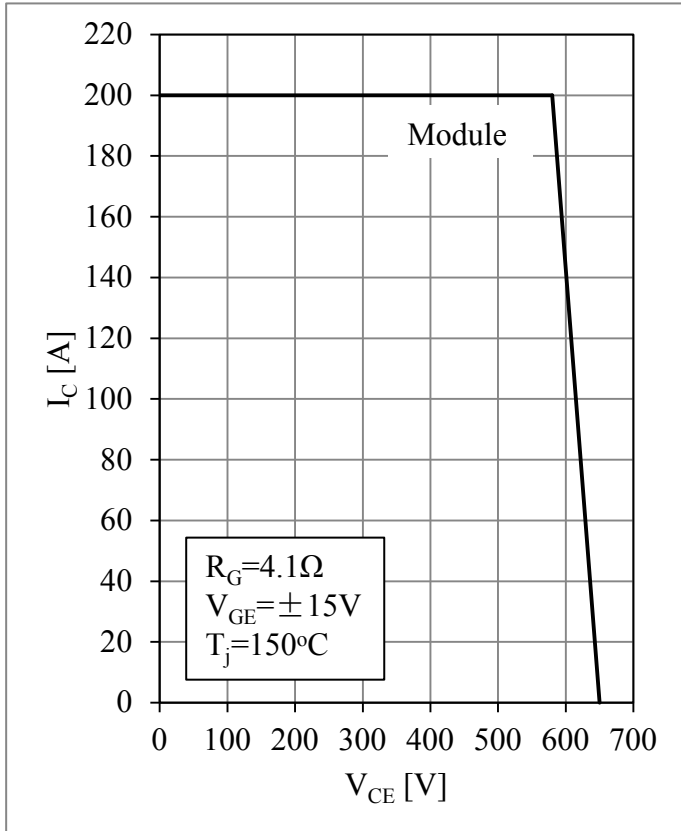


Fig 19. T4,T7 RBSOA

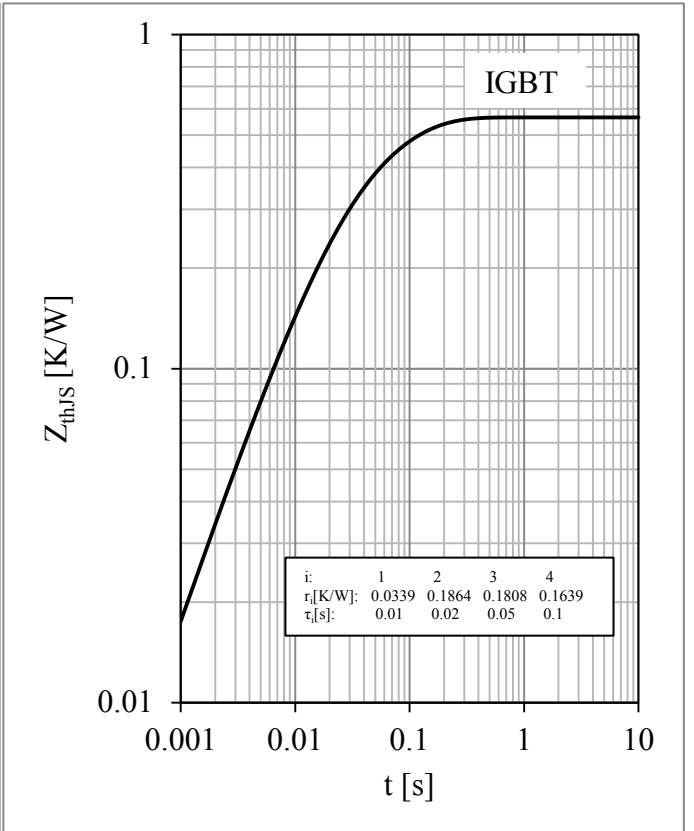


Fig 20. T4,T7 IGBT Transient Thermal Impedance

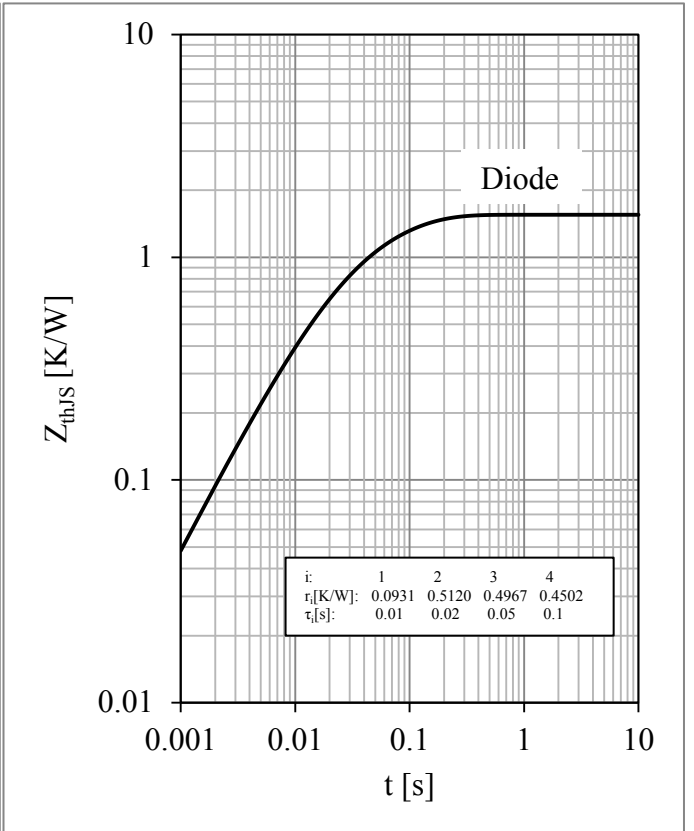
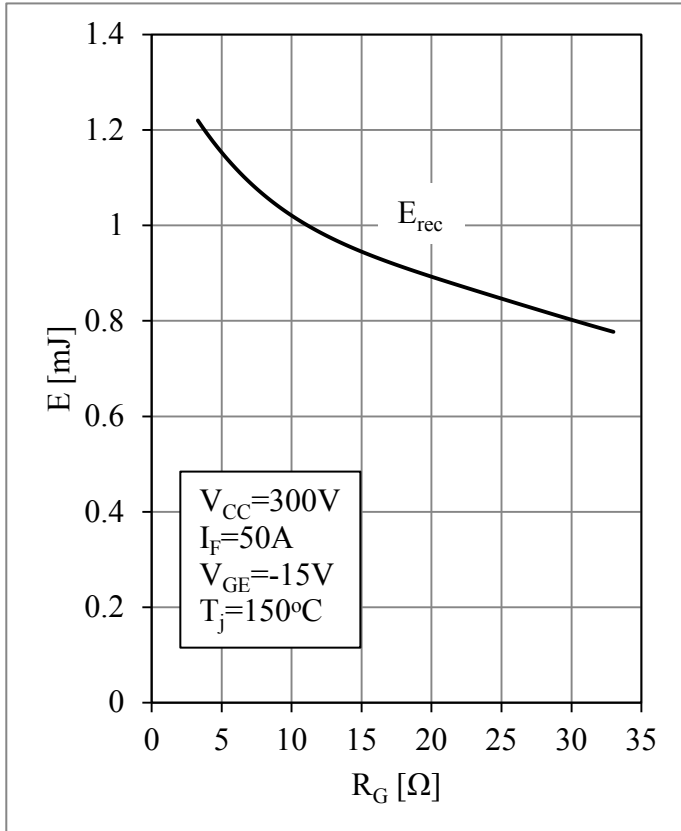
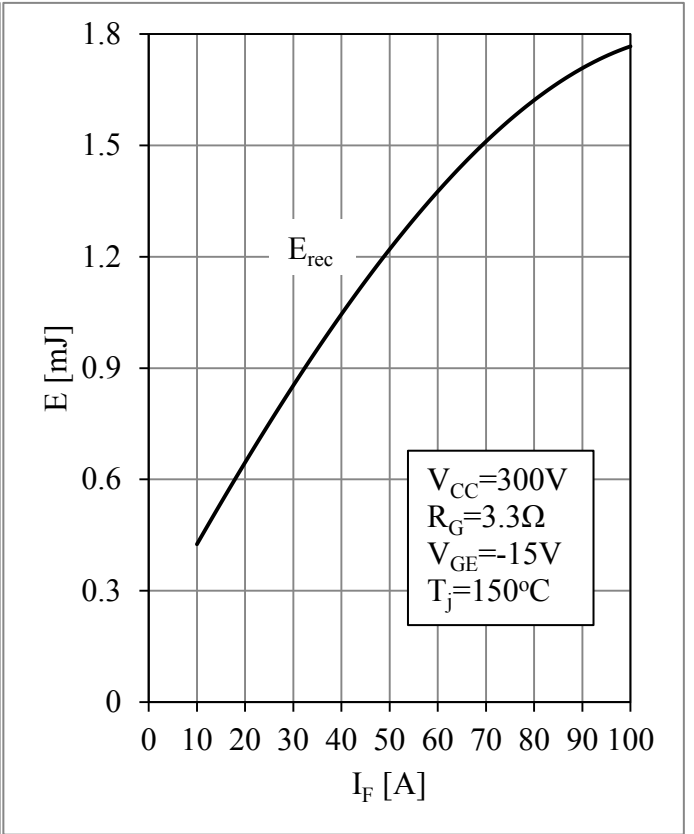
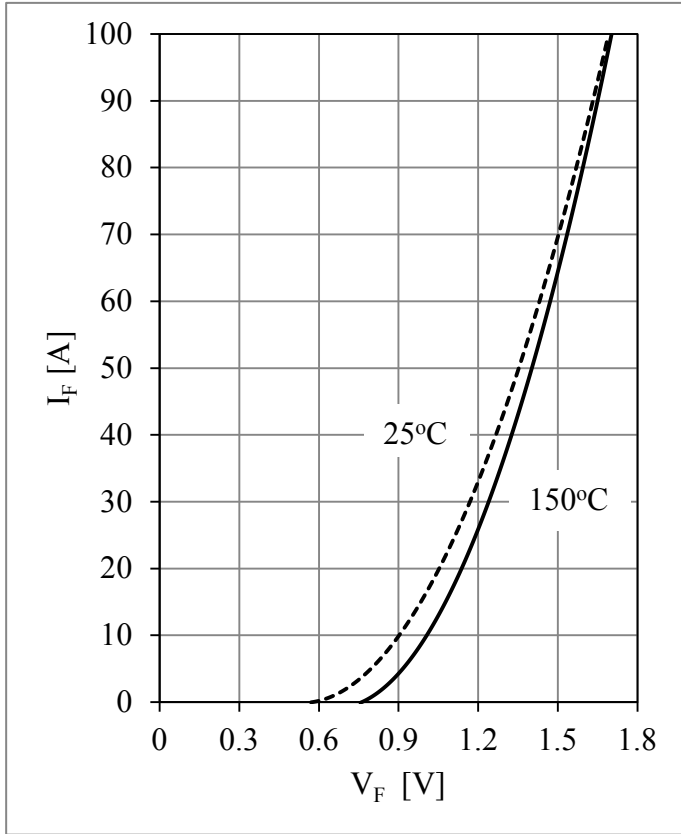


Fig 23. D4,D7 Diode Switching Loss vs. R_G

Fig 24. D4,D7 Diode Transient Thermal Impedance

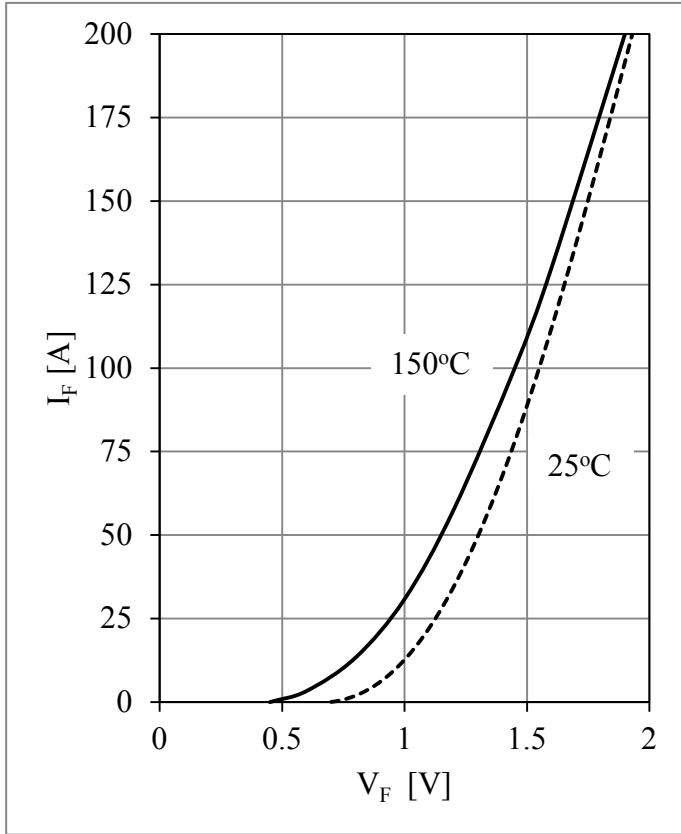


Fig 25. D3,D8 Diode Forward Characteristics

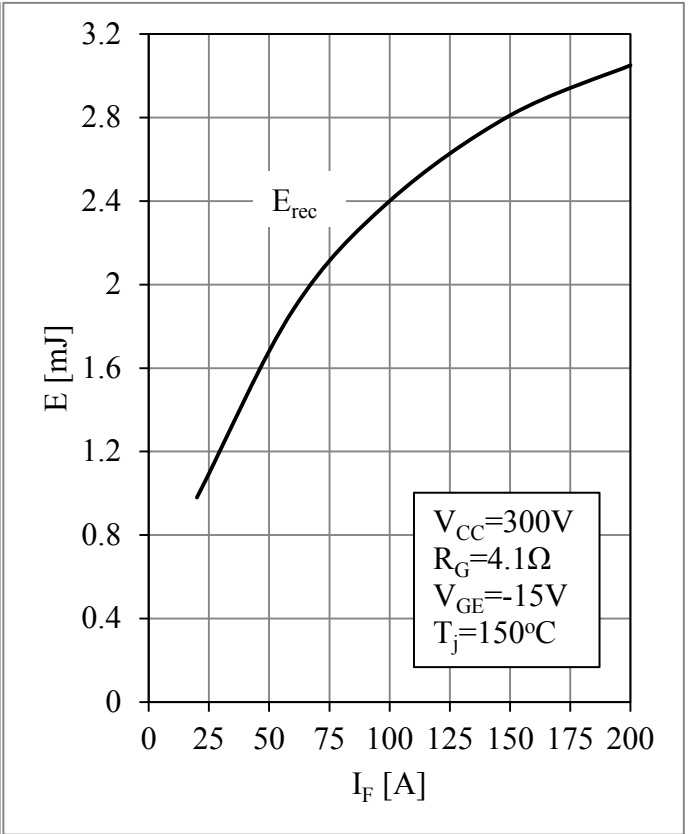


Fig 26. D3,D8 Diode Switching Loss vs. I_F

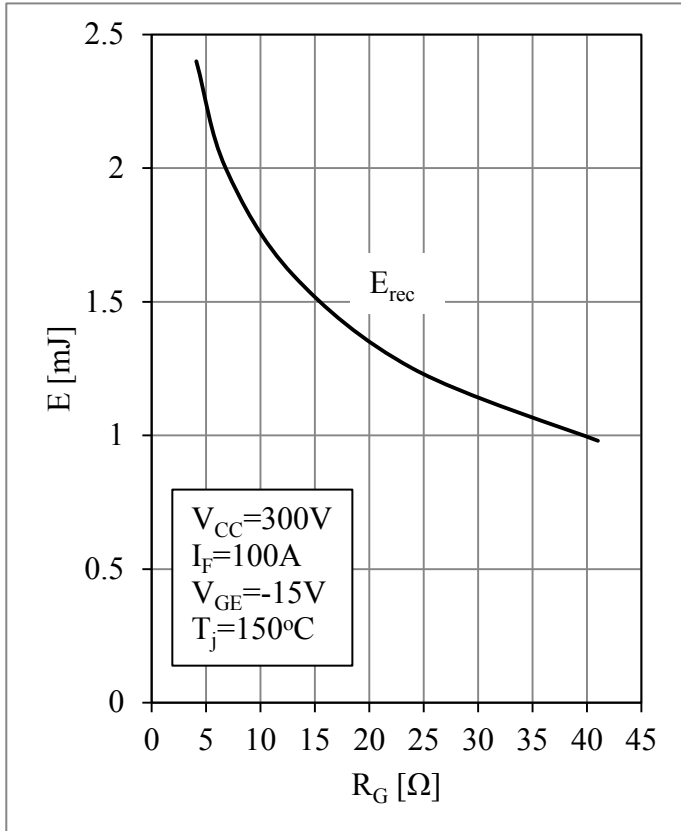


Fig 27. D3,D8 Diode Switching Loss vs. R_G

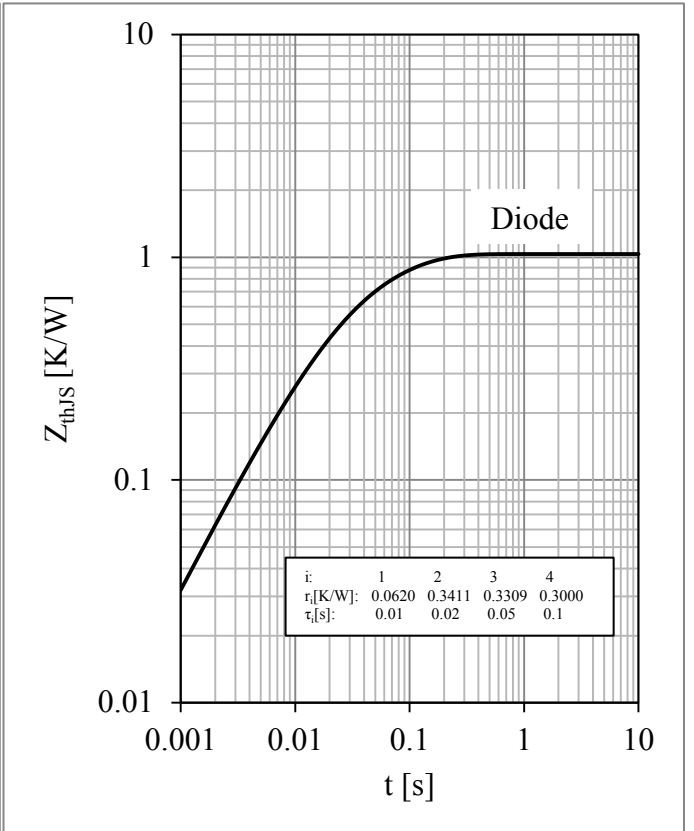


Fig 28. D3,D8 Diode Transient Thermal Impedance

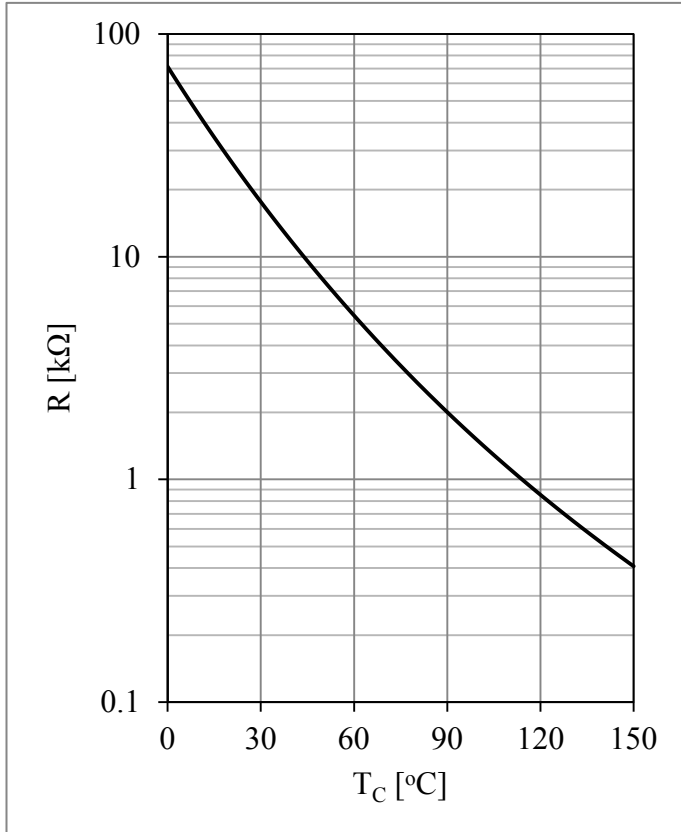
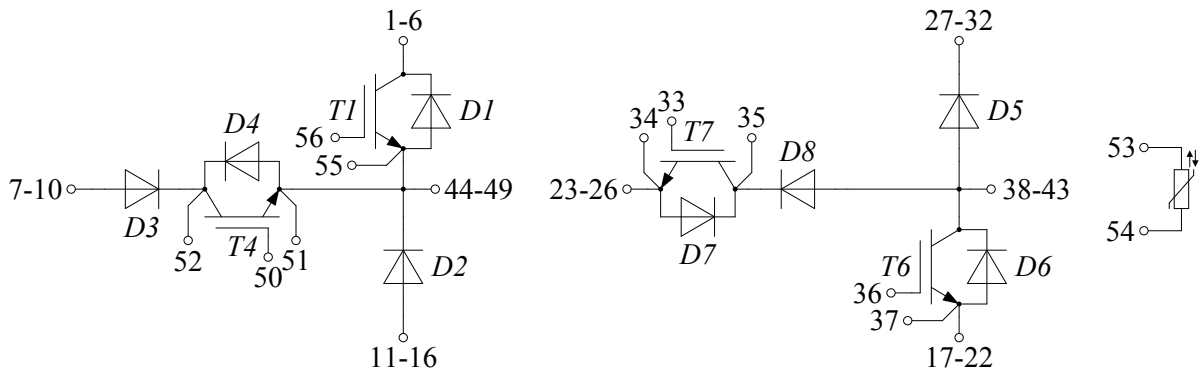


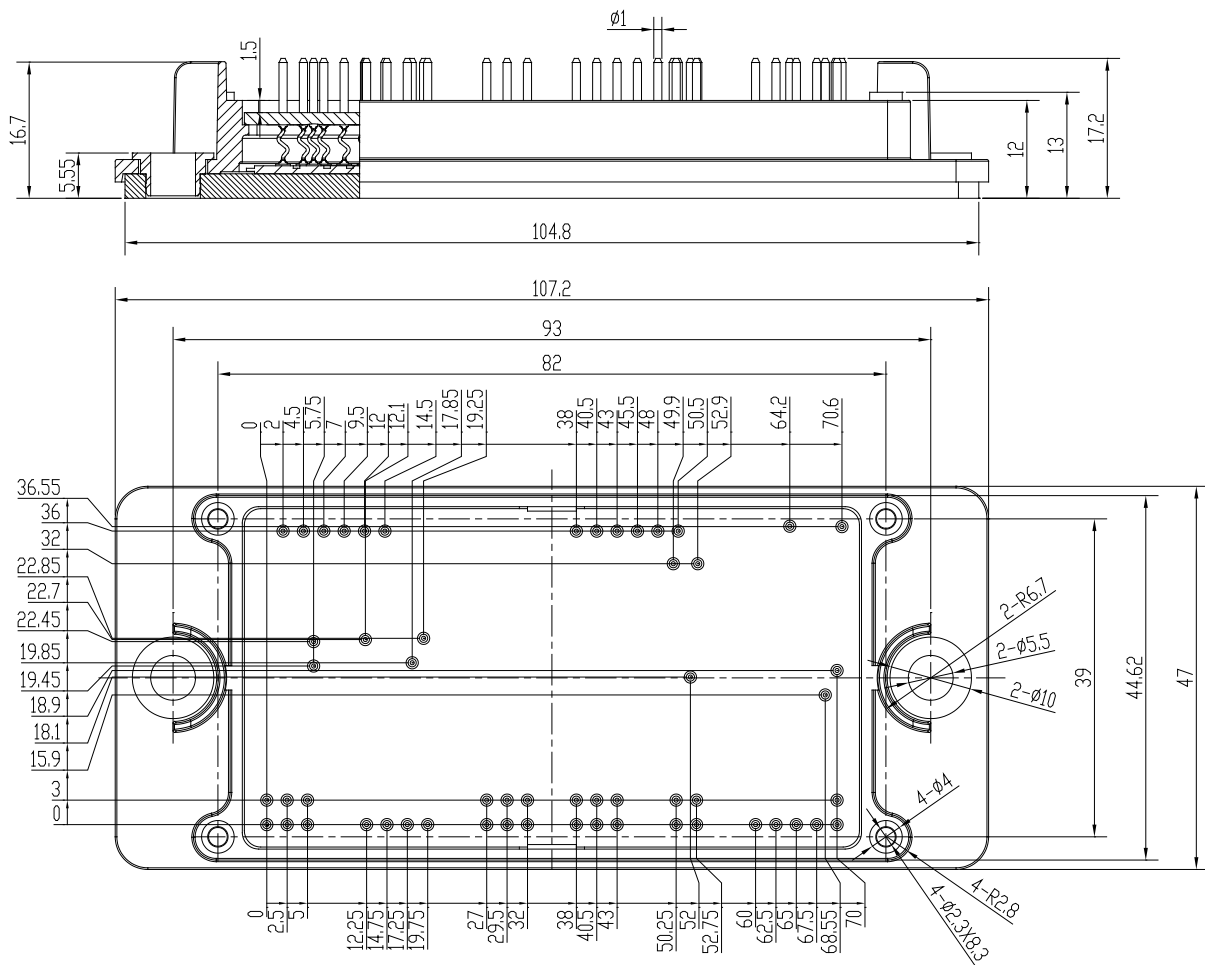
Fig 29. NTC Temperature Characteristic

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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